

Two microchips are shown. The chip on the left is green with the word 'DAY' printed in white. The chip on the right is also green but has four yellow square pads on its surface.

Operation Temperature	-40 °C to +85 °C
Storage Temperature	-45 °C to +85 °C
Terminating Impedance	50Ω

Electronic Characteristics		
Item	Frequency (MHz)	Specification
Center Frequency fo	1575.42	
Pass-band Width	±2.2	
Insertion Loss		2.3 dB Max.
Pass-band Ripple		0.6 dB Max.
VSWR		2.0 Max.
Guaranteed Attenuation	824 to 960 MHz	45 dB Min.
	1475.42 MHz	40 dB Min.
	1525.42 MHz	35 dB Min.
	1625.42 MHz	35 dB Min.
	1675.42 MHz	50 dB Min.
	1710 to 1880 MHz	45 dB Min.
	1850 to 1990 MHz	40 dB Min.
	1920 to 2170 MHz	40 dB Min.

The drawing illustrates the mechanical specifications of the DAY package. The top view shows a square package with a width of 2.5 ± 0.1 mm and a height of 2.0 ± 0.1 mm. The side view indicates a thickness of 0.8 ± 0.2 mm. The bottom view shows the pin layout with dimensions: pin pitch of 0.63 mm, pin width of 0.325 mm, and pin spacing of 1.325 mm. The package is labeled with 'DAY' and 'C0.3'.

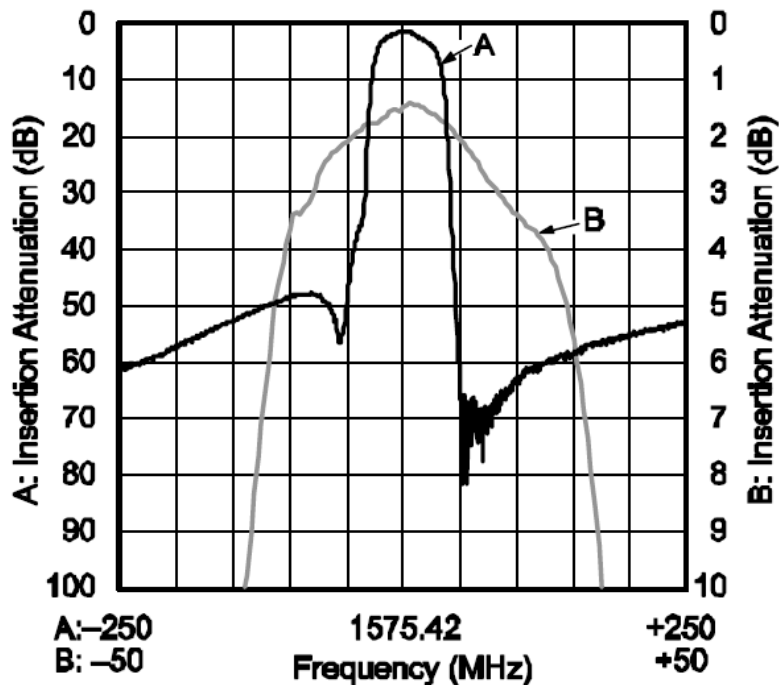
Pin	Connection
#1	INPUT
#2	GND
#3	OUTPUT
#4	GND

Unit:mm

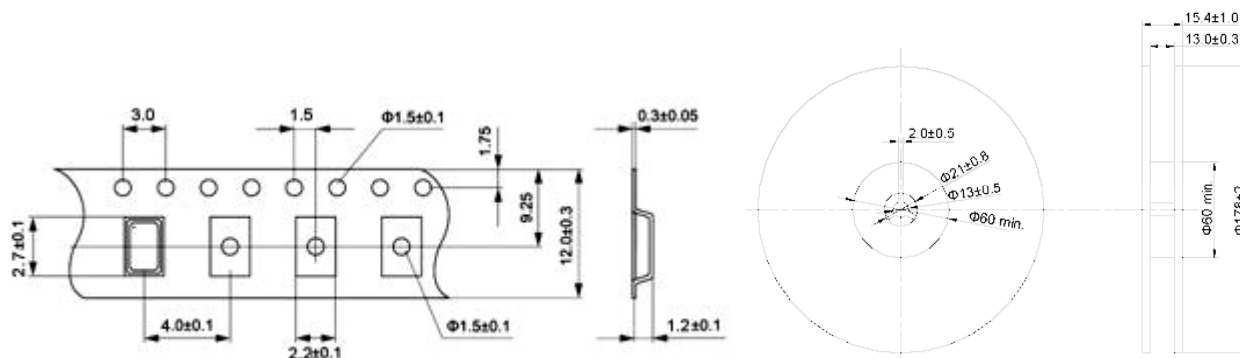
SAW Filters

SF 2520B

Frequency Characteristics

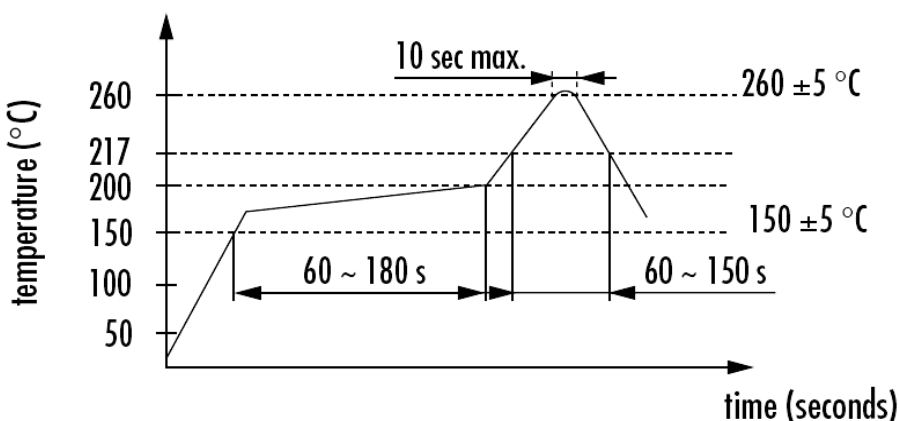


Tape Specifications



3000pcs/Reel

Reflow Soldering Profile



SAW Filters		SF 2520B
Reliability		
Mechanical Shock		The components shall remain within the electrical specifications after three one-half sine shock pulses(300g's for 0.3 ms) in each direction(for six total) along each of the three mutually perpendicular axes for a total of 18 shocks.
Vibration Fatigue		The components shall remain within the electrical specifications after loaded vibration at 20 to 55 Hz, amplitude 1.5mm, X,Y,Z direction, for 2 hours.
Leak Test	Gross Leak Test	Submerge samples into at +85°C water for at least 1 minute. Carefully observe the samples. No bubbles should be seen.
	Fine Leak Test	Expose samples for testing to 60 PSIG Helium gas for 2 hours. Then transfer the same samples to another chamber and draw a vacuum. Measure the leak rate. Failure is defined if the leak rate exceeds 5×10^{-8} atm cc/sec Helium.
High Temperature Storage		The components shall remain within the electrical specifications after being kept at the 85°C±2°C for 960 hours, then kept at room temperature for 2 hours.
Low Temperature Storage		The components shall remain within the electrical specifications after being kept at the -40°C±2°C for 960 hours, then kept at room temperature for 2 hours.
Temperature Cycle		The components shall remain within the electrical specifications after 32 cycles of high and low temperature testing (one cycle:80°C for 30 minutes →25°C for 20 seconds →-40°C for 30 minutes) then kept at room temperature for 2 hours.
Humidity Test		The components shall remain within the electrical specifications after being kept at the condition of ambient temperature 70°C, and 90~95% RH for 240 hours, then kept at room temperature and normal humidity for 4 hours.
Solder-heat Resistance		The components shall remain within the electrical specifications after dipped in the solder at 260°C±5°C for 10 to 11 seconds, then kept at room temperature for 10 minutes.
Solderability		Solderability of terminal shall be kept at more than 80% after dipped in the solder flux at 230°C±5°C for 5±1 seconds.
Storage		The components shall meet the electrical and mechanical specifications after 5 years storage, if stored within the temperature range of -40°C to +85°C and in the humidity of 20 to 60% RH.

Remarks

Static voltage	Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.
Ultrasonic cleaning	Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.
Soldering	Only leads of component may be soldered. Please avoid soldering another part of component.

